

# Smart GaN-Based Inverters for Grid-tied Energy Storage Systems

DOE/OE Peer Review, 09/25/2019



DOE SBIR Phase IIB



U.S. DEPARTMENT OF  
**ENERGY**



**Sandia**  
National  
Laboratories

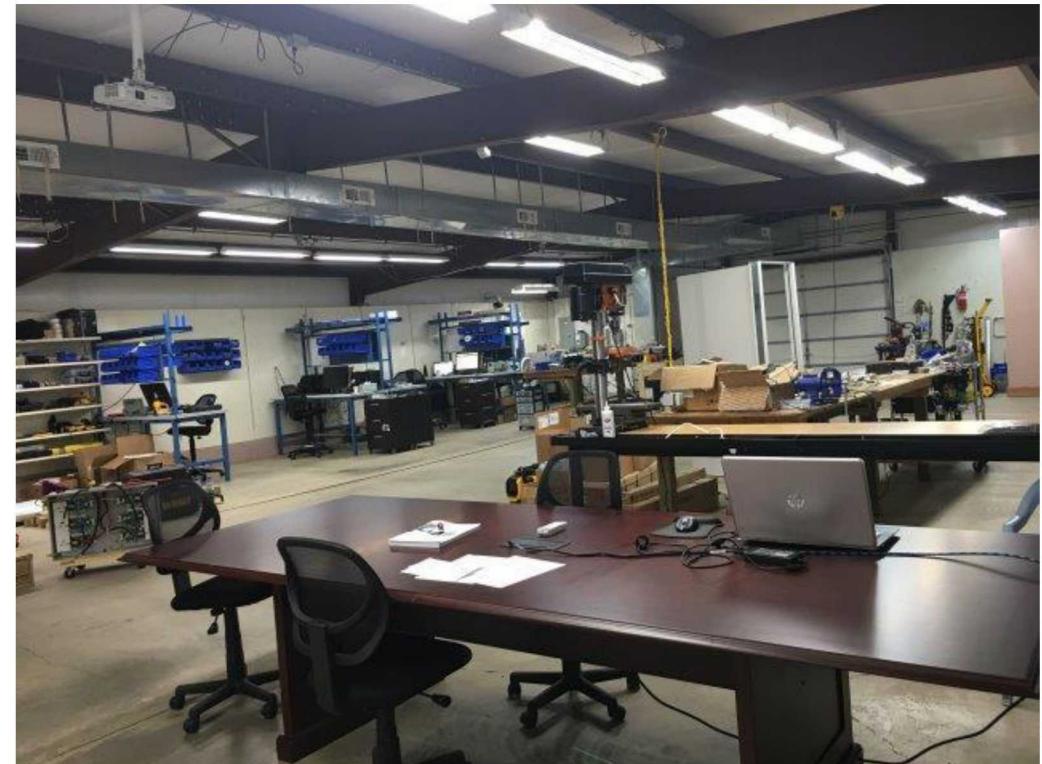
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# Acknowledgement

InnoCit greatly appreciates support of Dr. Imre Gyuk and Dr. Stan Atcitty through DOE SBIR grant DE-SC0013818.

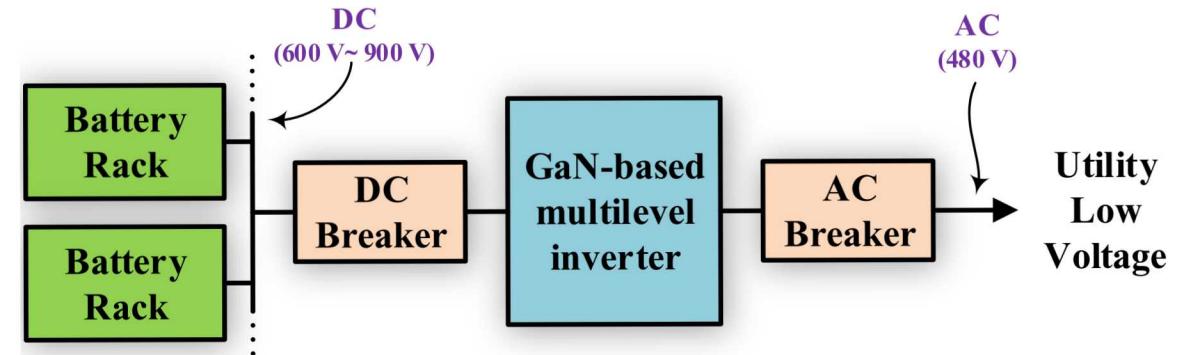
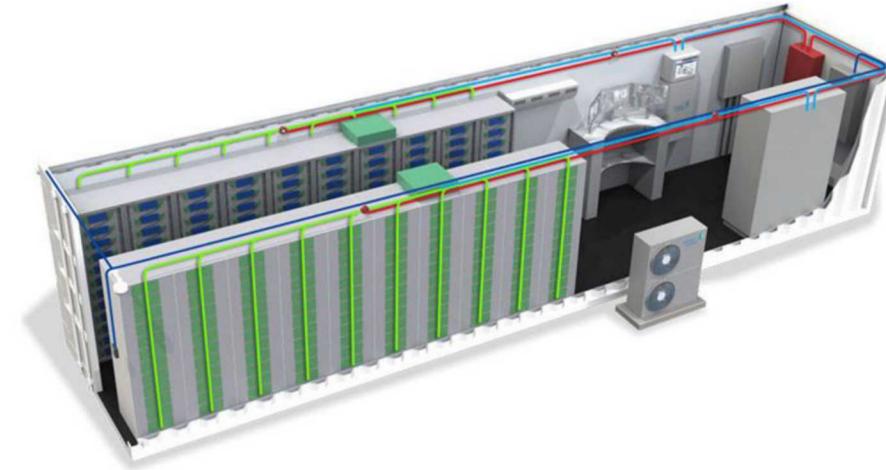
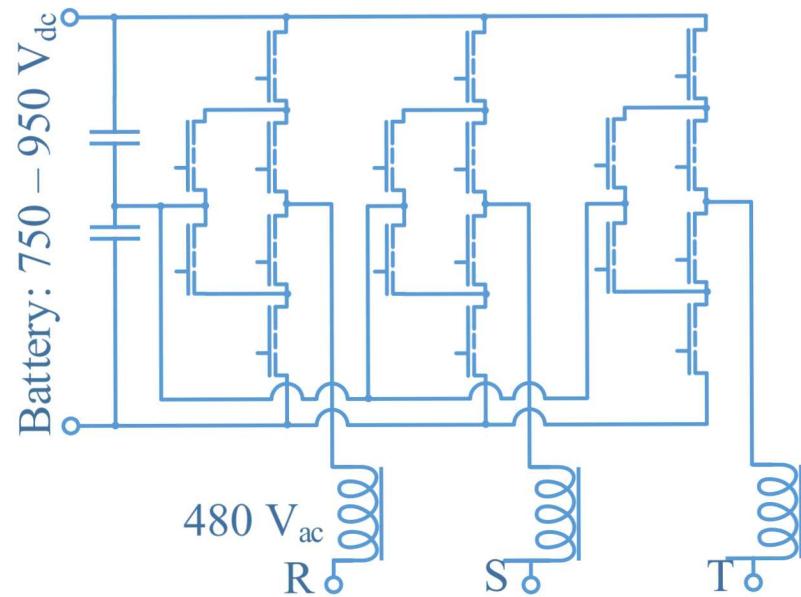


- Founded in 2014
- Tech Transfer Startup
- 4,000 sq. ft. research facility, 10 acre campus, solar farm, based in Missouri
- DOE SBIR Phase I, II, IIB, NSF SBIR Phase I
- Costume manufacturing



# System Specifications

- **GaN-based multilevel inverter**
- **Nominal input voltage: 900V**
- **Output voltage: 3-phase 480V**
- **Power rating: 20kW to 200kW**



# Specific Objectives

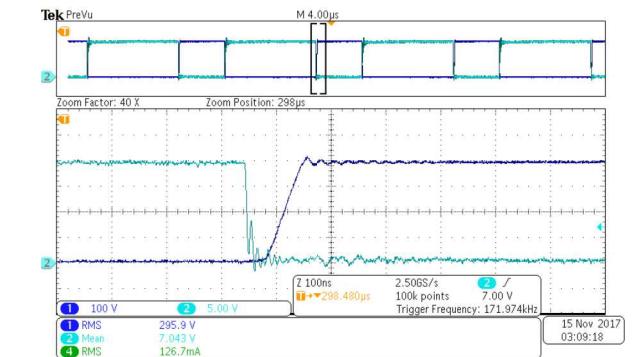
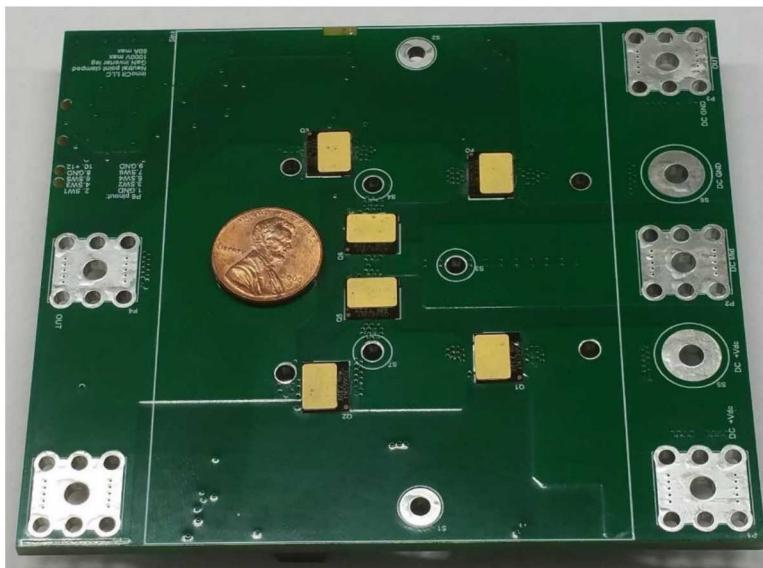
- **Designing 3U rack-chassis-based enclosures for inverter modules**
- **Conduct thermal analysis on the enclosures**
- **Controls and hardware for hot-swap capabilities**
- **Validate final metrics: efficiency of at least 98.6%, weight < 2.2 lb./kW, volume <0.1 ft<sup>3</sup>/kW, noise <45 dBA**
- **Reliability testing including active bypass and hot-swap features**
- **IEEE 1547, UL 1741, and 1741-SA testing for islanding and fault ride-through**
- **UL certification testing**
- **Remote control and monitoring backbone structure development**

# Fast-Paced Technology

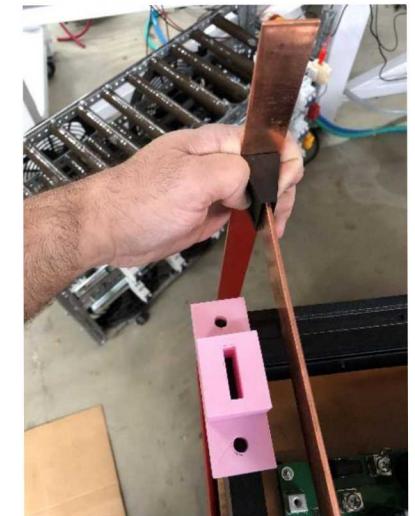
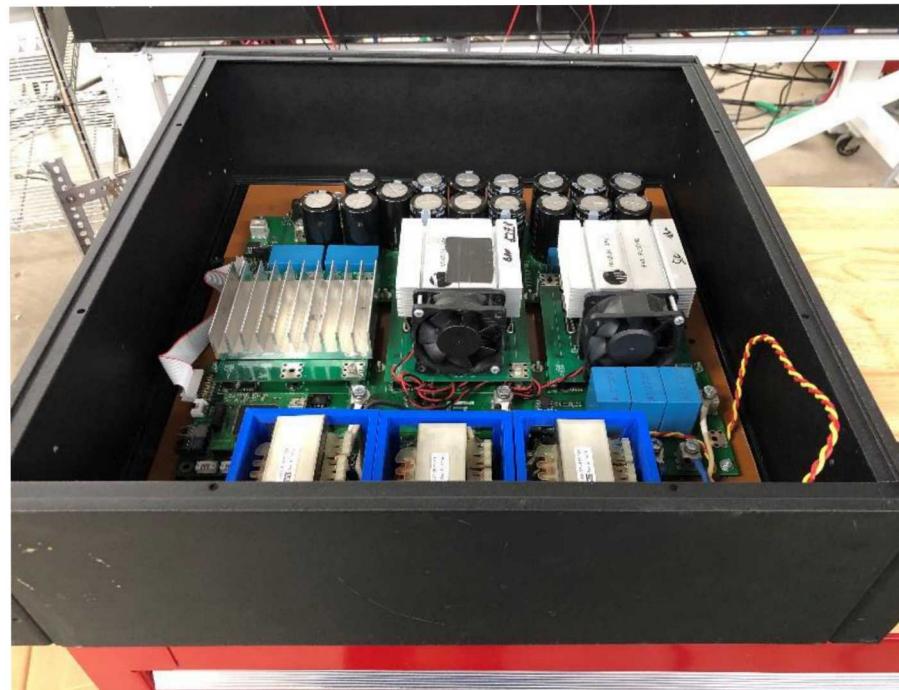
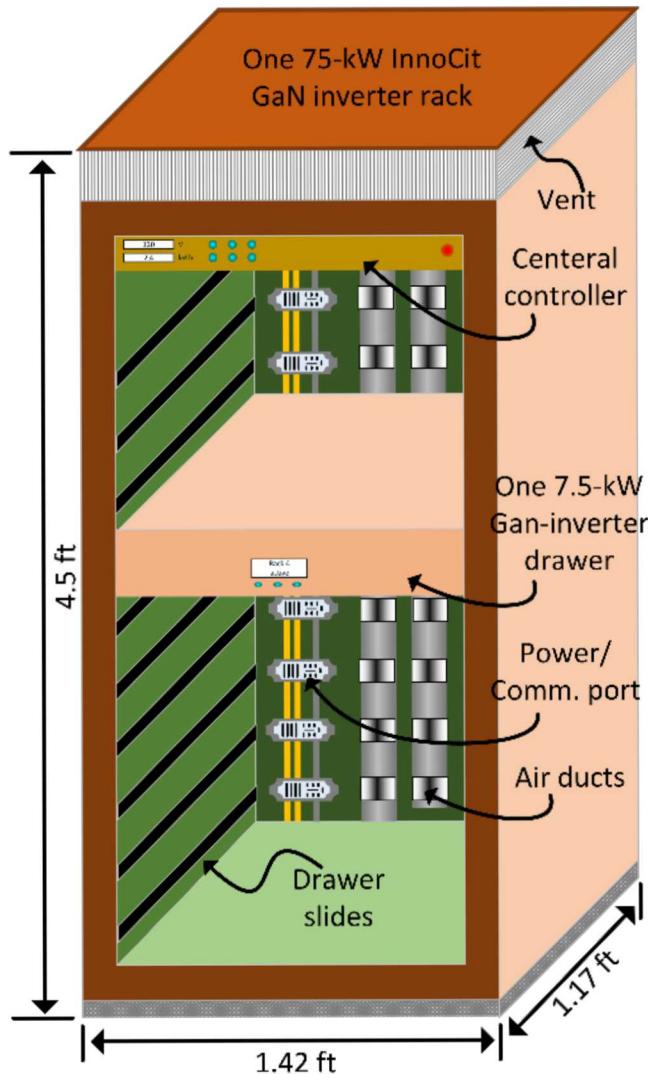
| Technology / manufacturer  | Transphorm                    | EPC                  | GaN systems          | GaN systems          |
|----------------------------|-------------------------------|----------------------|----------------------|----------------------|
| Switch topology            | Cascode: GaN JFET + Si MOSFET | Enhancement mode FET | Enhancement mode FET | Enhancement mode FET |
| Material                   | GaN + Si                      | GaN                  | GaN                  | GaN                  |
| Part number                | TPH3205WS                     | EPC2034              | GS66508T             | GS66516T             |
| Voltage                    | 600 V                         | 200 V                | 650 V                | 650 V                |
| Current                    | 36 A                          | 31 A                 | 30 A                 | 60 A                 |
| R <sub>ds-on</sub> @ 150°C | 0.10 Ω                        | 0.015 Ω              | 0.050 Ω              | 0.025 Ω              |
| CRSS (Reverse transfer)    | 17.5 pF                       | 5 pF                 | 2 pF                 | 4 pF                 |
| Heatsink Plate             |                               | no                   | Yes                  | Yes                  |

# Achievements

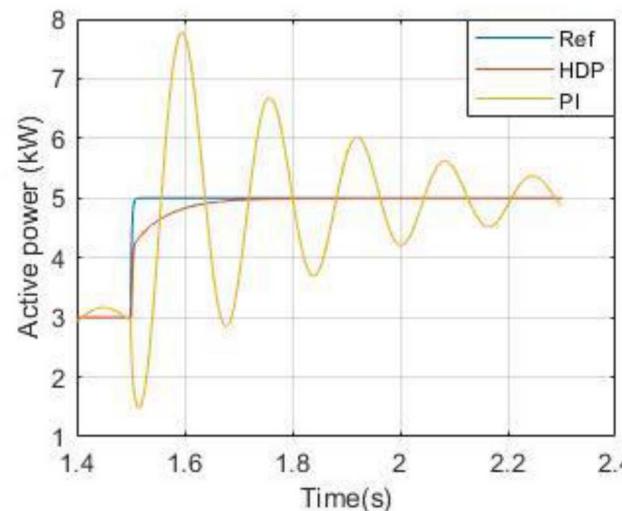
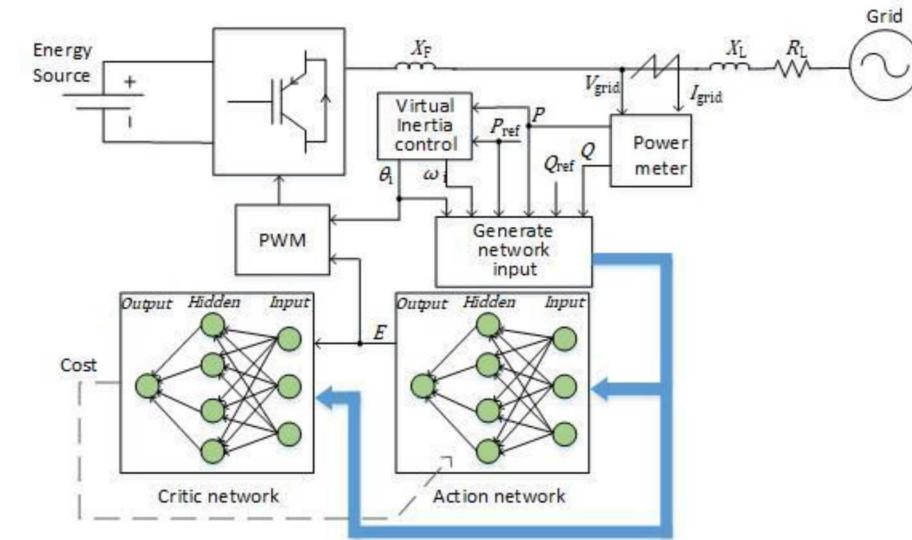
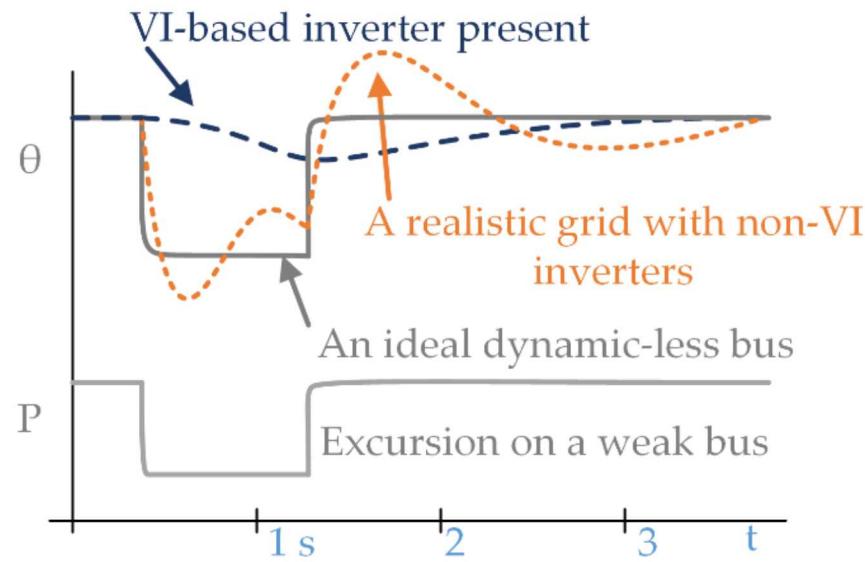
- First ever floating supply integrated GaN gate driver + switch (commercialized)
- First ever modular GaN-based 20-kW inverter (TRL-6)



# Final System



# Intelligent Inverter



# Commercial Competitiveness

| Features\Manufacturer         | InnoCit<br>Ganverter (10<br>units)         | Princeton Power<br>BIGI-250 | ABB<br>ESSpro-C250 | DynaPower<br>MPS-100 |
|-------------------------------|--|-----------------------------|--------------------|----------------------|
| <b>Total Power Rating (S)</b> | 200-kVA                                    | 265-kVA                     | 200-kVA            | 100-kVA              |
| <b>CEC Efficiency</b>         | 99%  | 94.5%                       | >94%               | 93.9%                |
| <b>Volume</b>                 | 30-ft <sup>3</sup> (full<br>system + rack) | 150-ft <sup>3</sup>         | 41-ft <sup>3</sup> | 48-ft <sup>3</sup>   |
| <b>Weight</b>                 | 540-lbs. (full<br>system + rack)           | 3500-lbs.                   | 2100-lbs.          | 1545-lbs.            |
| <b>Current THD</b>            | <2%  | <5%                         | <5%                | <5%                  |
| <b>End-user Price per VA</b>  | \$0.085/VA                                 | \$0.44/VA                   | \$0.58/VA          | \$0.52/VA            |

# Lessons Learned

- Gate driver design is very critical
- Requires isolated gate drivers and isolated dc-dc power supplies for driving the gate
- When selecting the isolated gate driver and gate power supply, one should ensure that they can withstand the high dv/dt stress due to faster turn ON and OFF times
- With the fast switching of GaN E-HEMTs, any parasitic inductances in the gate switching loop will give rise to ringing which leads to losses and EMI problems - keep the PCB gate-source loop as small as possible
- Best switching performance can be achieved with proper selection of gate resistor

# Lessons Learned

- Poor thermal conductivity of GaN semiconductor calls for special attention to thermal design
- GaN E-HEMTs have tiny packaging compared to SiC. Therefore, the heat generated within the device has to be dissipated fast and effectively to keep the junction temperature within allowable limits
- Also, the maximum junction temperature of the GaN E-HEMT selected is low compared to the SiC device
- If using a single heat sink for multiple GaN devices, they have to be aligned flat with the surface of heat sink
- Using thermal grease along with thermal tape will provide the best thermal conductivity

# Contact Information

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